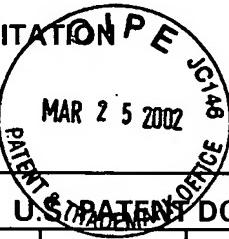


FORM PTO-1449

7059

Docket Number (Optional)
5694/CPI/COPPERApplication Number
10/074,855INFORMATION DISCLOSURE CITATION
IN AN APPLICATION

(Use several sheets if necessary)

Applicant
PERRINFiling Date
February 11, 2002

Group Art Unit

U.S. PATENT DOCUMENTS

EXAMINER INITIAL	DOCUMENT NUMBER							DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
<i>Jm</i>	4	1	1	6	7	9	1	9/26/78	Zega	427	524	
	4	7	7	4	4	3	7	9/27/88	Helmer, et al.	315	111.81	
	4	8	6	5	7	1	2	9/12/89	Mintz	204	299.16	
	4	9	6	0	7	5	3	10/2/90	Collins, et al.	204	299.04	
	5	1	5	8	6	6	0	10/27/92	Devigne, et al.	204	299.21	
	5	1	7	8	7	3	9	1/12/93	Barnes, et al.	204	MA 192.146	SEARCHED
	5	2	8	8	9	7	1	2/22/94	Knipp	219	192.57	
	5	5	0	5	7	8	0	4/9/96	Dalvie, et al.	16C	723MA	
	5	6	8	1	4	3	4	10/28/97	Eastlund	204	156	
	5	7	7	2	7	7	2	6/30/98	Chi	118	723MA	
	6	0	7	7	4	0	6	6/20/00	Kawakubo, et al.	204	299.12	
	6	1	5	0	6	2	8	11/21/00	Smith, et al.	219	121.54	
<i>Jm</i>	6	2	5	1	2	4	2	6/26/01	Fu, et al.	204	299.19	

FOREIGN PATENT DOCUMENTS

	DOCUMENT NUMBER							DATE	COUNTRY	CLASS	SUBCLASS	Translation	
												YES	
<i>Jm</i>	9	9	0	0	8	2	3	1/7/99	PCT				full
<i>Jm</i>	61	2	8	4	5	7	3	12/15/86	JP				abstract

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)

<i>Jm</i>	Chapman, Brian. "Glow Discharge Processes: Sputtering & Plasma Etching," John Wiley & Sons, NY, 1980: pp. 257-258.
	Kitamoto, Y., et al. "Compact Sputtering Apparatus for Depositing Co-Cr Alloy Thin Films in Magnetic Disks," Proc. of the 4 th ISSP, Japan, 1997: pp. 519 - 522.
	Musil, J., et al. "Unbalanced Magnetrons and New Sputtering Systems with Enhanced Plasma Ionization," J. Vac. Sci. Tech., A 9 (3), May/June 1991; pp. 1171 - 1177.
<i>Jm</i>	Yamazato, M., et al. "Preparation of TiN Thin Films by Facing Targets Magnetron Sputtering," Proc. of the 4 th ISSP, Japan, 1997: pp. 635 - 638.

EXAMINER	DATE CONSIDERED
<i>Robery Mc Donald</i>	10/6/03

EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP § 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to the applicant.